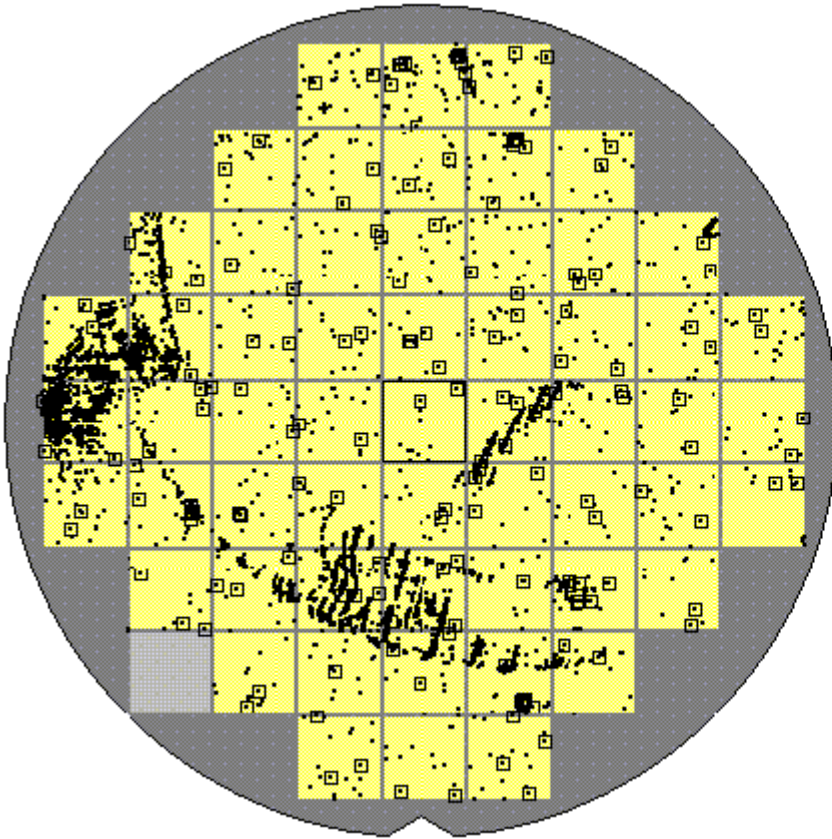


# Description of Work

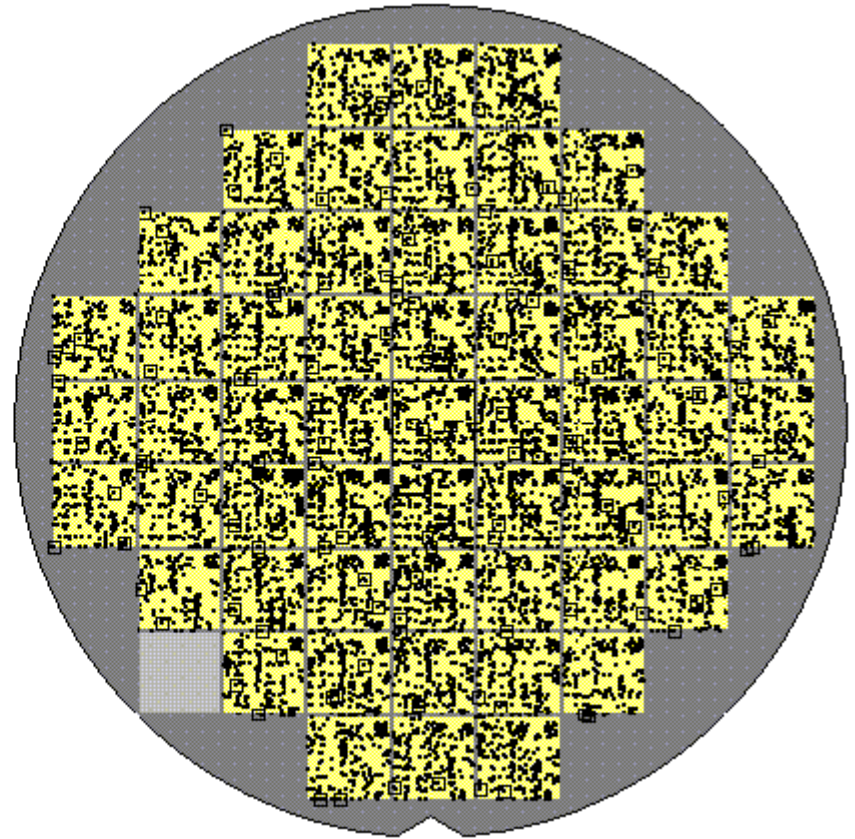
- Two wafers were submitted for KLA2139 defect inspection post Copper CMP using an MIT854 pattern.
- A recipe was created to catch all defect types present on these wafers.
- Images were captured on a sample of defects from each wafer.
- A sample of defects were reviewed in a review SEM to characterize defect types.
- Defects were classified manually using a combination of SEM and optical images.

# Wafer Maps

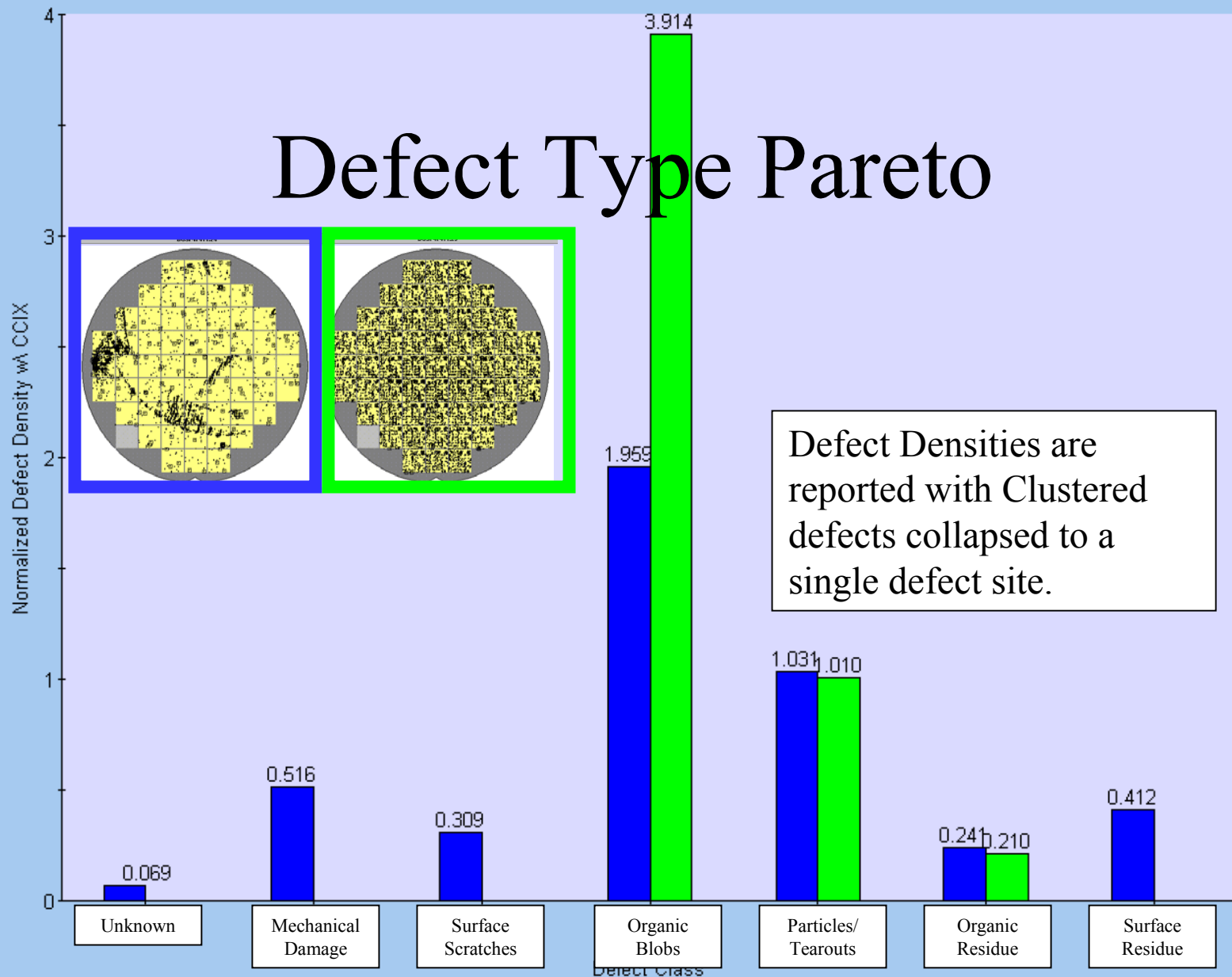
BGSF47411:24



BGSF47411:25



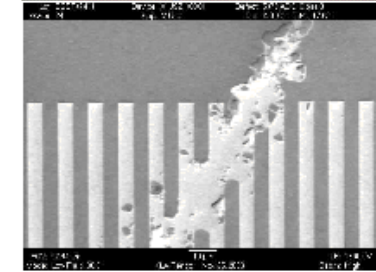
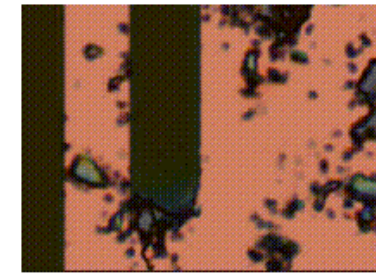
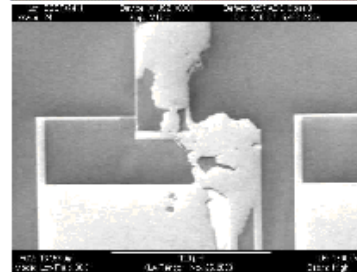
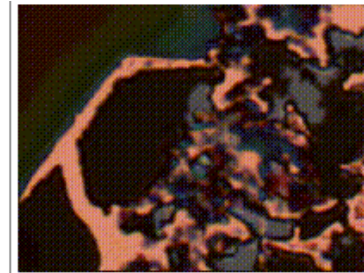
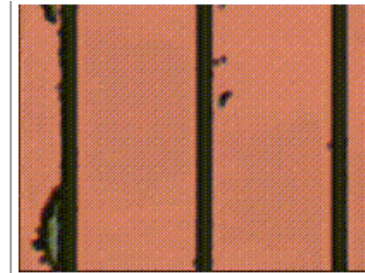
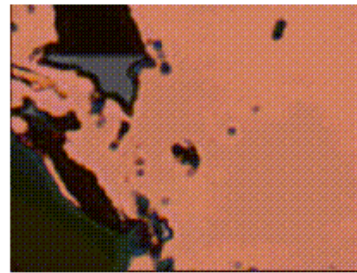
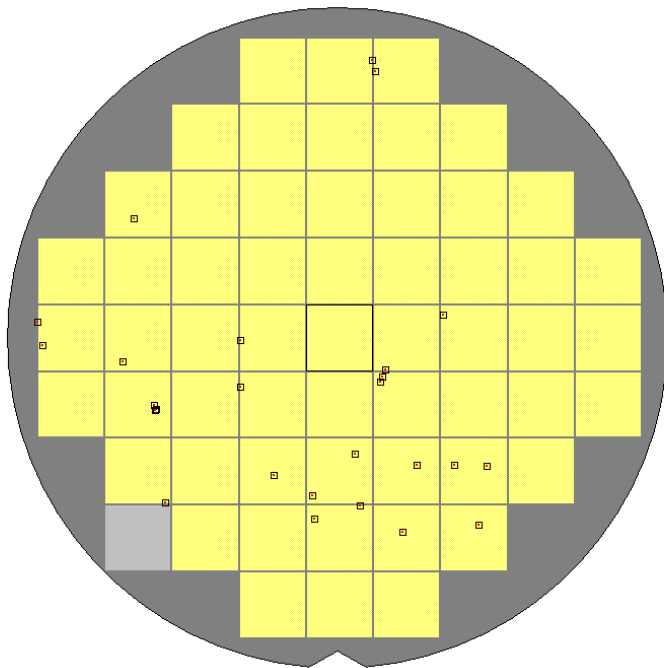
# Defect Type Pareto



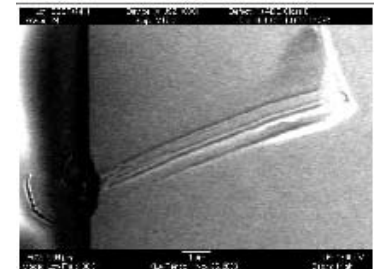
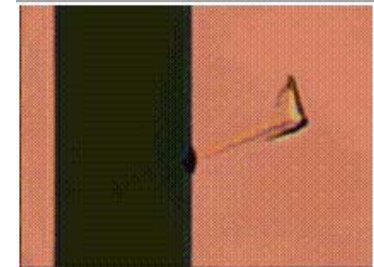
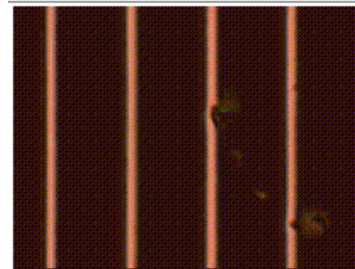
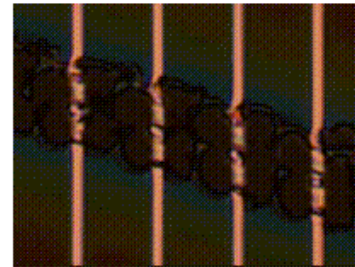
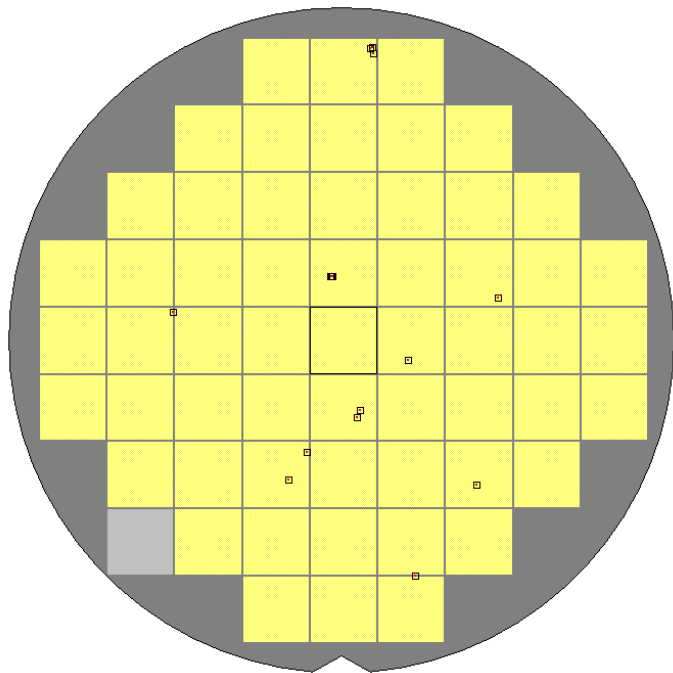
■ BGSF47411:24

■ BGSF47411:25

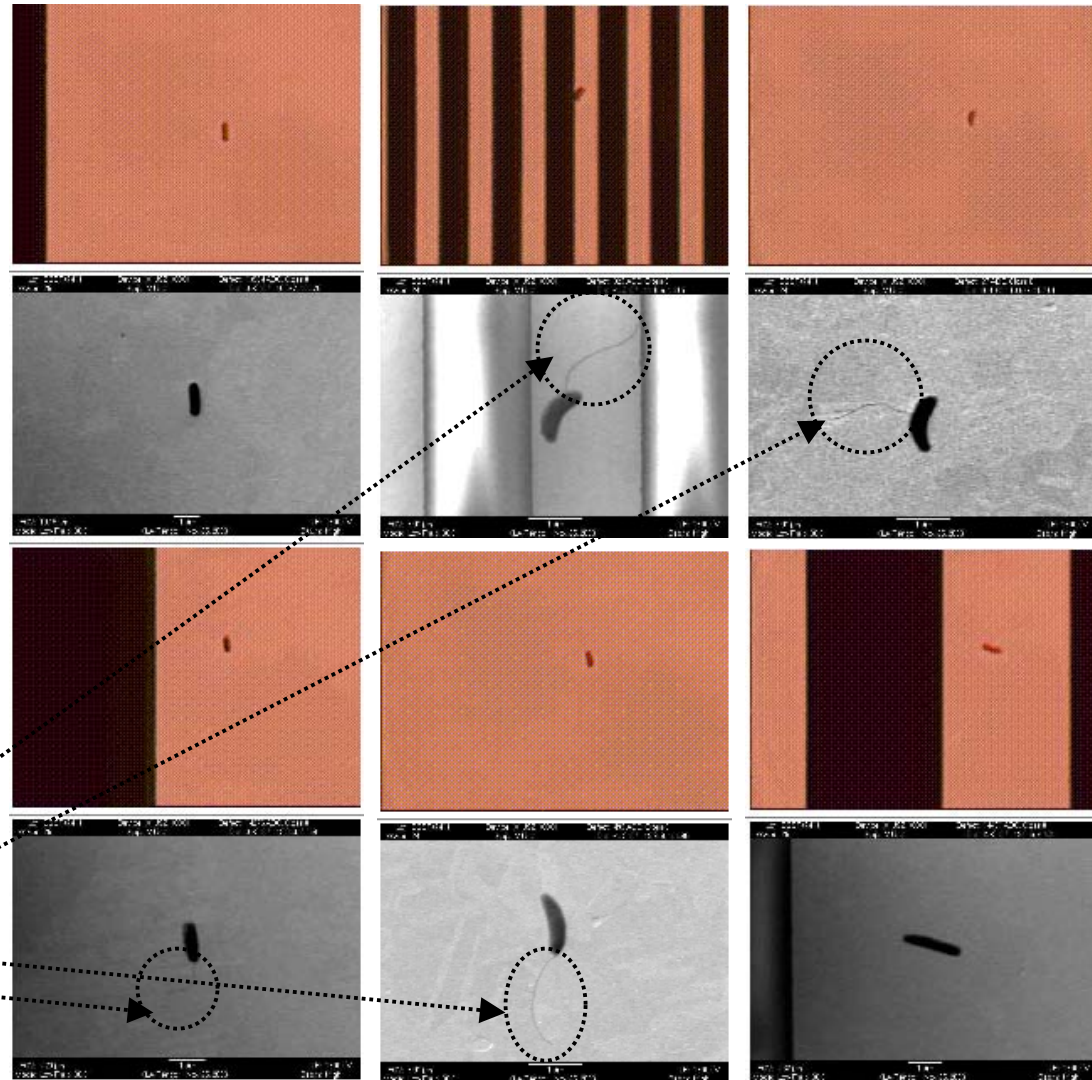
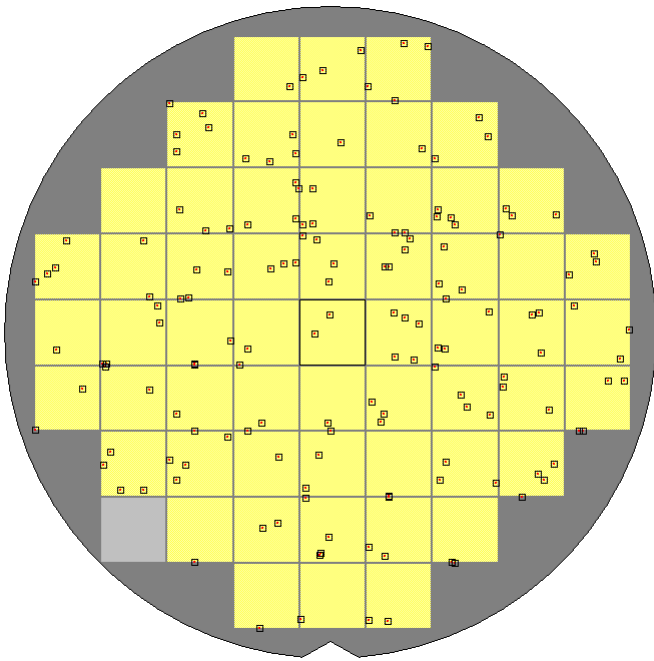
# Defect Class #100: Mechanical Damage



# Defect Class #101: Surface Scratches

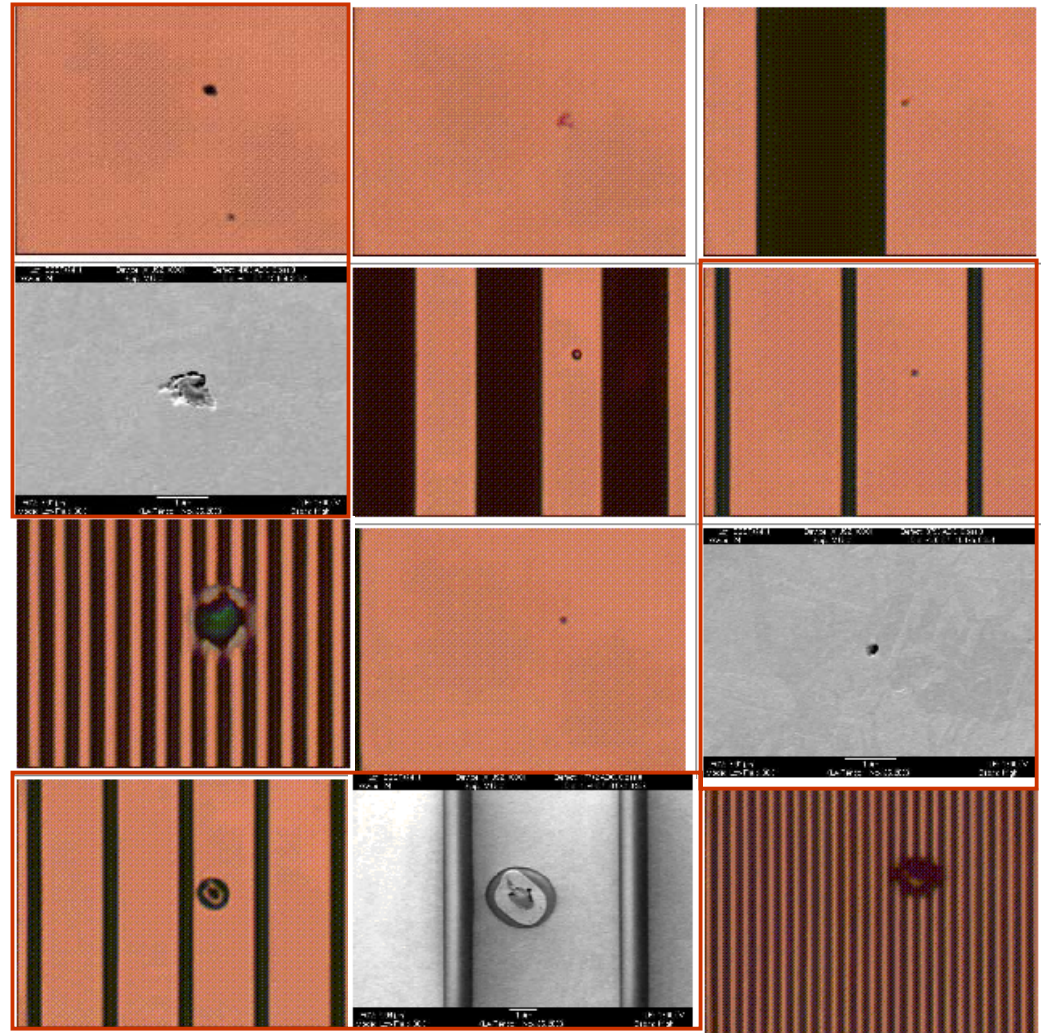
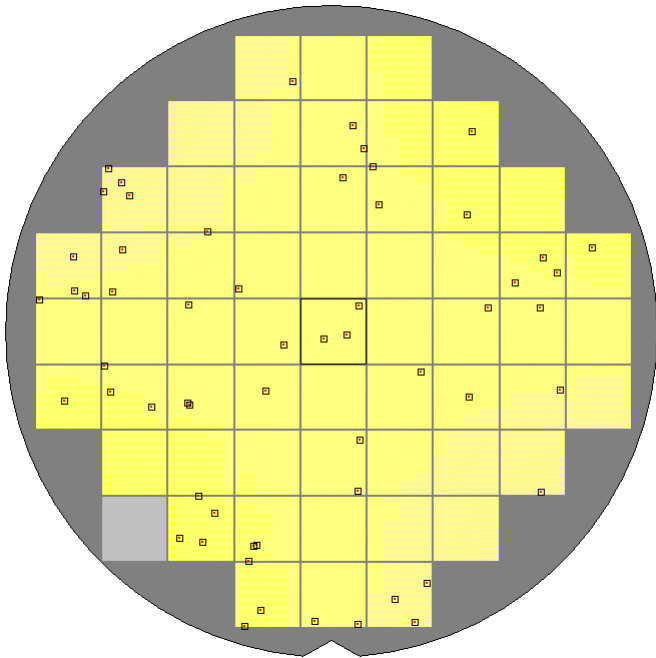


# Defect Class #102: Organic Blobs

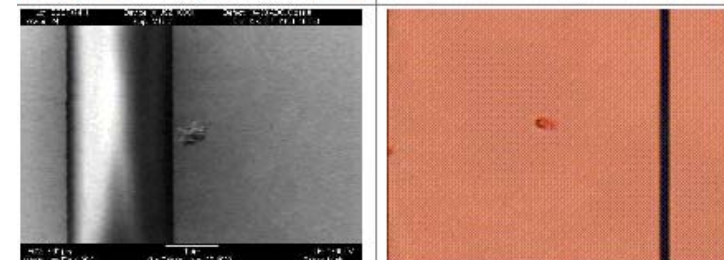
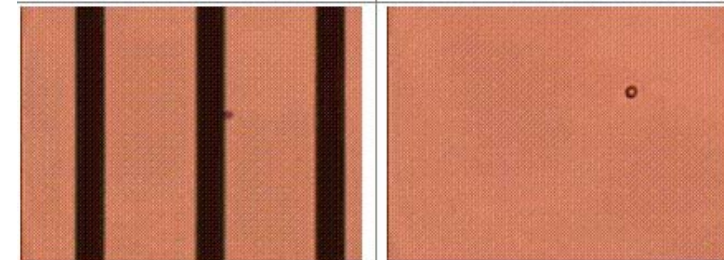
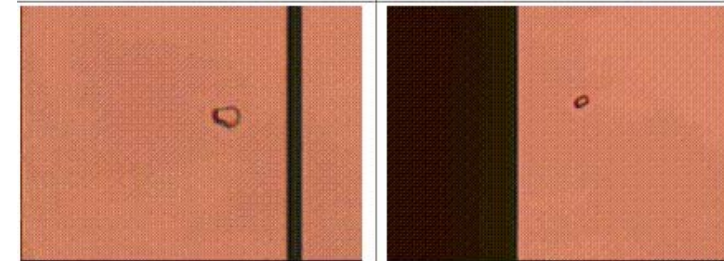
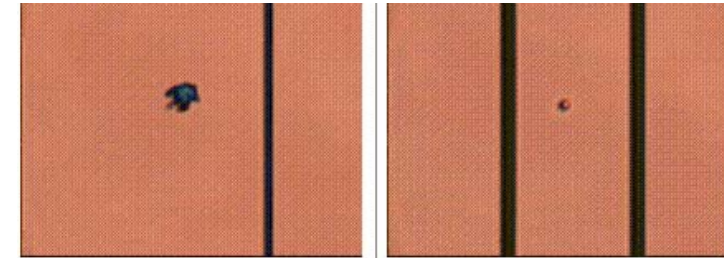
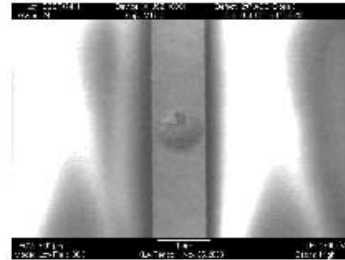
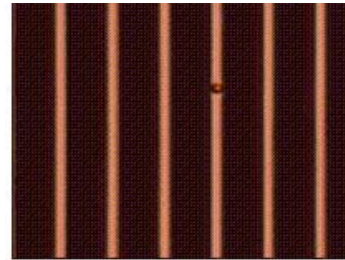
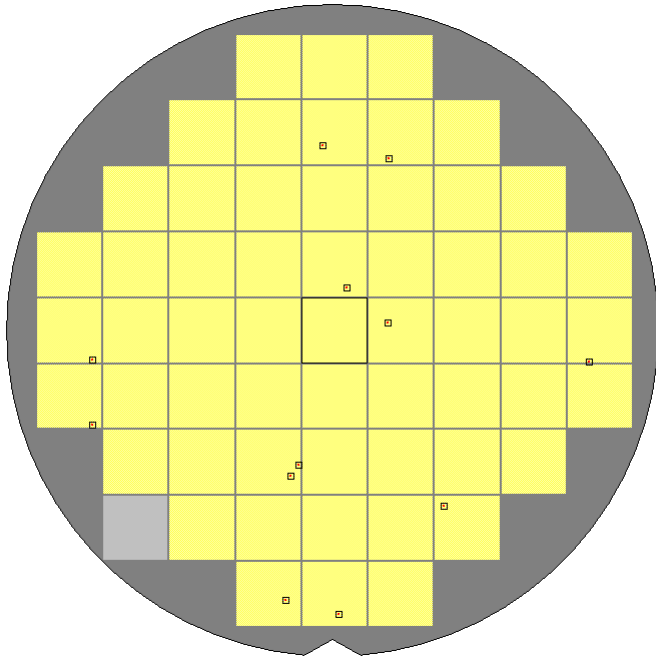


Many of these defects have a defined "tail" when viewed in an SEM, suggesting that these defects might be biological in origin

# Defect Class #103: Particles/Tearouts



# Defect Class #104: Organic Residue



# Defect Class #105: Organic Residue

